

99-2 Preliminary Syllabus, Da-Yeh Univ

Information			
Title	電子封裝概論	Serial No. / ID	1837 / MAI4024
Dept.	機械與自動化工程學系	School System / Class	大學日間部4年4班
Lecturer	鄭江河	Full or Part-time	專任
Required / Credit	Optinal / 3	Graduate Class	Yes
Time / Place	(二)56 / H466 (三)9 / H466	Language	Chinese

Introduction
Electronic packages is a rear process of semiconducting manufacture industry. This course will cover the principle of plastic packages and ceramic packages. Lecture materials will provide students a clear and thorough understanding of the type automation bonding, ball array grid, anisotropic conductive paste and the flip chip packages. The adequate ability to analyze the electronic packages of key components in the semiconducting manufacture industry will be developed.

Outline
<ol style="list-style-type: none">1. Introduction2. Plastic Package3. Ceramic Package4. Thin/ Thick Film Technologies5. Tape Automated Bonding (TAB)6. Flip-Chip (FC)7. Anisotropic Conductive Film (ACF)8. Multi Chip Modules (MCM)9. Chip Scale Package (CSP)

Prerequisite
Semiconductor Processing Technology, Introduction to Microelectromechanical Systems